



# SMART DESOLDER 01

## Standalone 480 W device

The SMART DESOLDER combines a manual hot gas source with a vacuum pen for extraction of residual solder. Damage to the pads from overheating or mechanical stress is avoided through targeted heating of the residual solder after lifting the component. The temperature-controlled airflow prevents the neighboring components from warming up. After melting, the residual solder is removed contactlessly by the vacuum pen. The soft Teflon tip

prevents damage to the pads through mechanical demands. As a standalone device, it virtually fits on any work bench and can be operated very flexibly with two handheld pens. The HOTBEAM 04 / 05 under-heating system perfectly completes the SMART DESOLDER 01. Through this combination, the temperature behavior can be optimized by way of a sensor-supported or programmed preheating profile.

### Top Features

Manual hot-gas source with a vacuum pen



#### Process safety

The soft and antistatic Teflon tip prevents damage to the pads through high mechanical or electrical demands



#### Plug and Play

Compact format, innovative design and intuitive operation



#### Temperature control

The temperature-controlled airflow prevents the pads from overheating as well as neighboring components from heating up



#### Process control

Solder pen's controlled airflow between 5-25 l/min



#### Performance

HOTBEAM and SMART DESOLDER combination for the perfect rework

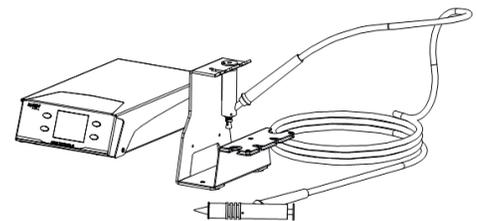


#### Flexibility

Intuitive use, with two handheld pens

### Standard equipment

- Two handheld pens with magazine for soldering and residual solder removal
- Solder nozzle 4 mm
- Solder removal nozzle complete with Teflon tip 1.4 mm
- Cleaner solder removal nozzle
- Flux filter and solder separator for old solder

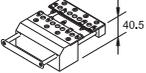


### Technical details

<b>Power consumption:</b>	480 W
<b>Power solder pen:</b>	300 W, 25 l/min

<b>Mains:</b>	100 - 240 VAC, fuse TG, 3A
<b>Pressurized air:</b>	7.5 l/min max. 4 bar clean, dry air
<b>Dimensions:</b>	270 x 150 x 60 mm <sup>3</sup>

## SMART DESOLDER 01: Optional extras

	Article nr.	Name
	HF00.0004	Handy Fix 06 Base plate 280*380mm, 4x magnet holder, H=40,5mm
	HF00.0016	Handy Fix 06 Base plate 280*380mm 4x magnet holder h=55.5=>69,5mm adjustable
	SF03.0019	PCB clamping holder with 3 fingers for mobile phone pcbs on HB05/IRx/HIF h=40.5mm

## Equipment

	DV15.0012	Solder separator for old solder standard type, 1.4 / 1.0mm (with 5 masks)
	DV15.0030	Flux filter for cooler of solder sucker nozzle
	HT00.0019	Clean Pen for pads and IR glass with 3 spare erasers
	HT00.0119	Flux Creme lead free 18g 0506 MA, no clean, REL0, with brush
	DV15.0016	Solder sucker nozzle 0.5mm for μSMD/CSP/QFP, only teflon tip
	DV15.0015	Solder sucker nozzle 1.0mm for μSMD/CSP/QFP, only teflon tip
	DB50.0004	Soldering nozzle 7mm conical
	DB50.0002	Soldering nozzle 3mm
	DB50.0001	Soldering nozzle 2mm

More accessories and consumables at [www.martin-smt.de](http://www.martin-smt.de)